

SPECIFICATION OF BSFxxxxMCPGM SERIES

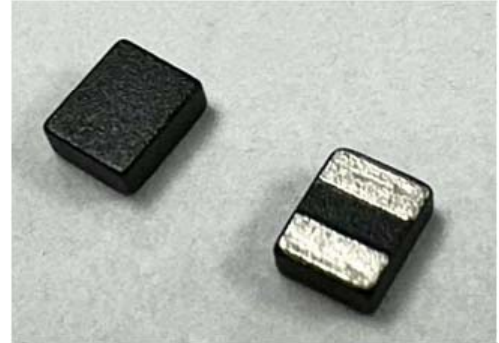
FEATURES

1. Metal material for large current and low loss.
2. High performance (Isat) realized by metal dust core.
3. Low loss realized with low Rdc.
4. Closed magnetic circuit design reduces leakage flux.
5. Vinyl thermal spray, better surface compactness.
6. RoHS compliant.



APPLICATIONS

DC/DC Converters .
 Pad, Smartphone.
 Portable gaming devices, Smart wear, Wi-Fi module.
 Notebooks, VR, AR.
 LCD displays, HDDs, DVCs, DSCs, etc.

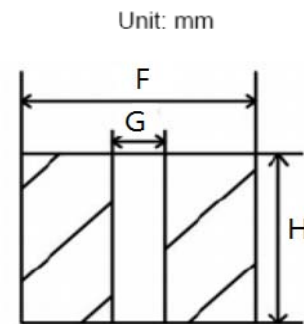
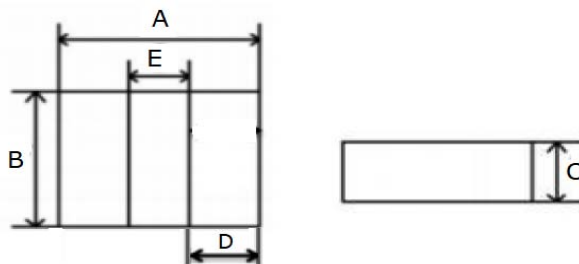


ORDERING CODE

BSF2512MCPGM 1R0 M T

(1) (2) (3)(4)

- (1) PRODUCT TYPE CODE AND SIZE CODE
- (2) INDUCTANCE
- (3) INDUCTANCE TOLERANCE (M : ±20%, N : ±30%)
- (4) REEL TAPING



Recommended Pad Layout

SHAPE & DIMENSIONS

SIZE CODE	A mm	B mm	C mm	D mm	E mm	F mm	G mm	H mm		
BSF1006MCPGM	1.0±0.1	0.7±0.1	0.65max	0.3±0.2	0.4±0.2	1.1	0.3	0.8		
BSF1206MCPGM	1.2±0.2	1.0±0.2	0.65max	0.4±0.2	0.4±0.2	1.3	0.3	1.1		
BSF1608MCPGM	1.6±0.2	0.8±0.2	0.80max	0.5±0.2	0.6±0.2	1.7	0.5	0.9		
BSF1408MCPGM	1.4±0.2	1.2±0.2	0.80max	0.45±0.2	0.5±0.2	1.5	0.4	1.3		
BSF201210MCPGM	2.0±0.2	1.2±0.2	1.0max	0.7±0.2	0.6±0.2	2.1	0.5	1.3		
BSF201610MCPGM	2.0±0.2	1.6±0.2	1.0max	0.7±0.2	0.6±0.2	2.1	0.5	1.7		

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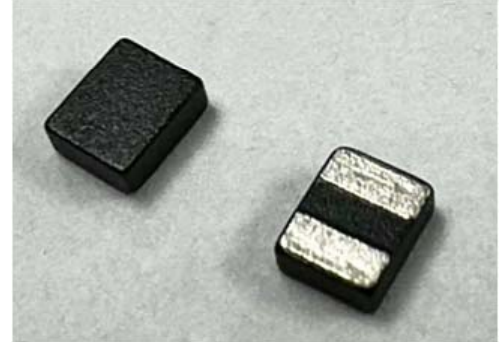
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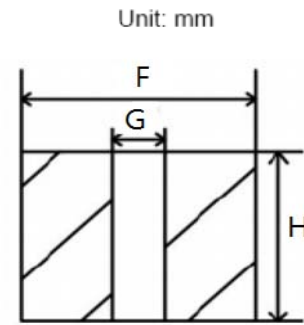
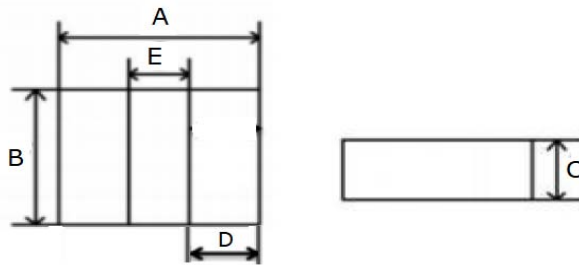


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Recommended Pad Layout

SHAPE & DIMENSIONS

SIZE CODE	A mm	B mm	C mm	D mm	E mm	F mm	G mm	H mm		
BSF2510MCPGM	2.5±0.2	2.0±0.2	1.0max	0.85±0.20	0.8±0.2	2.6	0.7	2.1		
BSF2512MCPGM	2.5±0.2	2.0±0.2	1.2max	0.85±0.20	0.8±0.2	2.6	0.7	2.1		
BSF3212MCPGM	3.2±0.2	2.5±0.2	1.2max	1.05±0.20	1.0±0.2	3.2	0.9	2.5		
BSF4012MCPGM	4.1±0.2	4.1±0.2	1.2max	1.4±0.2	1.3±0.2	4.1	1.1	4.1		

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